



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-12-11
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STW15N95K5	TSLW*VJL5B52	A	SHENZHEN B/E	2015-12-11
Amount	UoM	Unit type	ST ECOPACK Grade	
4430.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.75, 20.15, 5.15	2	THROUGH HOLE	
Comment	TO 247			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSLW*VJL5B52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	14.265	mg	supplier	die	Silicon (Si)	7440-21-3		13.673	mg	958500	3086
				supplier	metallization	Aluminium (Al)	7429-90-5		0.255	mg	17876	58
				supplier	Passivation	Silicon Nitride	12033-89-5		0.059	mg	4136	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.145	mg	10165	33
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	491	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.093	mg	6519	21
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.033	mg	2313	7
Leadframe	Copper & its alloys	2720.611	mg	supplier	alloy	Copper (Cu)	7440-50-8		2705.048	mg	994280	610620
				supplier	alloy	Iron (Fe)	7439-89-6		1.246	mg	458	281
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		2.275	mg	836	514
				supplier	metallization	Nickel (Ni)	7440-02-0		11.968	mg	4399	2702
				supplier	metallization	Phosphorus (P)	12185-10-3		0.074	mg	27	17
Soft solder	Solder	12.714	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	12.142	mg	955010	2741
				supplier	solder	Silver (Ag)	7440-22-4		0.318	mg	25012	72
				supplier	solder	Tin (Sn)	7440-31-5		0.254	mg	19978	57
				supplier	wire	Aluminium (Al)	7429-90-5		0.680	mg	998825	153
Bonding wires	Other inorganic materials	0.681	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	1175	0
				supplier	mold compound	Silica, vitreous	60676-86-0		1457.713	mg	870000	329055
				supplier	mold compound	Epoxy resin	25068-38-6		167.553	mg	100000	37822
Encapsulation	Other Organic Materials	1675.532	mg	supplier	mold compound	Phenol resin	29690-82-2		41.888	mg	25000	9456
				supplier	mold compound	Carbon Black	1333-86-4		8.378	mg	5000	1891
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.197	mg	1000000	1399
Connections coating	Solder	6.197	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.197	mg	1000000	1399